



灵星芯微 集成电路

深圳市灵星芯微电子科技有限公司

Shenzhen Lingxing Microelectronics Technology Co., Ltd.

Tab: 835-12-B4

Number:SN74LS139-AX-LJ-A044EN

SN74LS139 (LX)

Dual 2-to-4 Line Decoder/Demultiplexer

Product Specification

Specification Revision History:

Version	Date	Description
2012-06-A1	2012-06	New
2023-04-B1	2023-04	Update the template



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1、General Description

The SN74LS139 decodes two binary weighted address inputs (nA_0 , nA_1) to four mutually exclusive outputs ($n\bar{Y}_0$ to $n\bar{Y}_3$). Each decoder features an enable input ($n\bar{E}$). When $n\bar{E}$ is HIGH all outputs are forced HIGH. The enable input can be used as the data input for a 1-to-4 demultiplexer application. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

Features:

- Demultiplexing capability
- 2 independent 2-to-4 decoders
- Multifunction capability
- Suitable for memory decoding, data routing or code conversion
- Active LOW mutually exclusive outputs
- Specified from -40°C to $+125^{\circ}\text{C}$
- Packaging information: DIP16/SOP16/TSSOP16



Ordering Information:

Tube packing specifications:

Part number	Packaging form	Marking code	Tube quantity	Boxed tube quantity	Boxed quantity	Notes
SN74LS139N (LX)	DIP16	SN74LS139N	25 PCS/tube	40 tube/box	1000 PCS/box	Dimensions of plastic enclosure: 19.0mm×6.4mm Pin spacing: 2.54mm
SN74LS139ADR(LX)	SOP16	LS139A	50 PCS/tube	200 tube/box	10000 PCS/box	Dimensions of plastic enclosure: 10.0mm×3.9mm Pin spacing: 1.27mm
SN74LS139PW(LX)	TSSOP16	LS139	96 PCS/tube	200 tube/box	19200 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing: 0.65mm



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Reel packing specifications:

Part number	Packaging form	Marking code	Reel quantity	Boxed reel quantity	Notes
SN74LS139ADR(LX)	SOP16	LS139A	2500 PCS/reel	5000 PCS/box	Dimensions of plastic enclosure: 10.0mm×3.9mm Pin spacing:1.27mm
SN74LS139PW(LX)	TSSOP16	LS139	5000 PCS/reel	10000 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing:0.65mm

Note: If the physical information is inconsistent with the ordering information, please refer to the actual product.



2、Block Diagram And Pin Description

2.1、Block Diagram

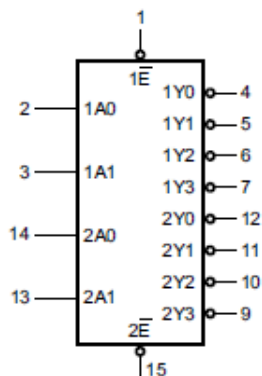


Figure 1. Logic symbol

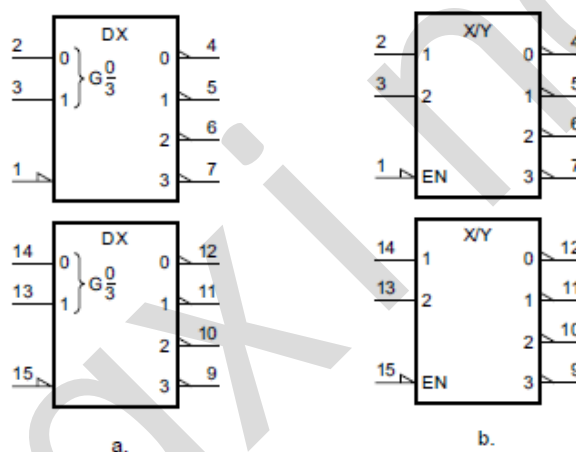


Figure 2. IEC logic symbol

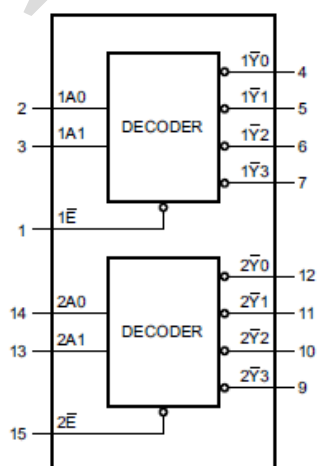


Figure 3. Functional diagram

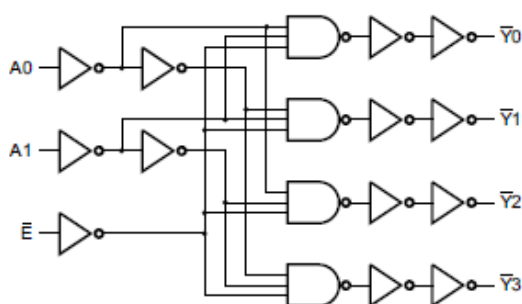
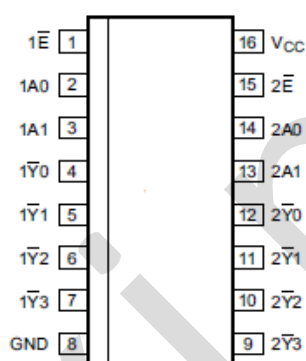


Figure 4. Logic diagram (one decoder/demultiplexer)

2.2、Pin Configurations



2.3、Pin Description

Pin No.	Pin Name	Description
1	$\bar{1E}$	enable input (active LOW)
2	1A0	address input
3	1A1	address input
4	$\bar{1Y0}$	output (active LOW)
5	$\bar{1Y1}$	output (active LOW)
6	$\bar{1Y2}$	output (active LOW)
7	$\bar{1Y3}$	output (active LOW)
8	GND	ground (0V)
9	$\bar{2Y3}$	output (active LOW)
10	$\bar{2Y2}$	output (active LOW)
11	$\bar{2Y1}$	output (active LOW)
12	$\bar{2Y0}$	output (active LOW)
13	2A1	address input
14	2A0	address input
15	$\bar{2E}$	enable input (active LOW)
16	V _{CC}	supply voltage



2.4、Function Table

Control	Input		Output			
	nA1	nA0	nY3	nY2	nY1	nY0
H	X	X	H	H	H	H
L	L	L	H	H	H	L
L	L	H	H	H	L	H
L	H	L	H	L	H	H
L	H	H	L	H	H	H

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care.

3、Electrical Parameter

3.1、Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}	-	-0.5	+7.0	V
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{CC}+0.5V$	-	± 20	mA
output clamping current	I_{OK}	$V_O < -0.5V$ or $V_O > V_{CC}+0.5V$	-	± 20	mA
output current	I_O	$V_O = -0.5V$ to $V_{CC}+0.5V$	-	± 25	mA
supply current	I_{CC}	-	-	50	mA
ground current	I_{GND}	-	-50	-	mA
storage temperature	T_{stg}	-	-65	+150	$^{\circ}C$
total power dissipation	P_{tot}	-	-	500	mW
soldering temperature	T_L	10s	DIP	245	$^{\circ}C$
			SOP/TSSOP	260	

3.2、Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t/\Delta V$	$V_{CC}=2.0V$	-	-	625	ns/V
		$V_{CC}=4.5V$	-	1.67	139	ns/V
		$V_{CC}=6.0V$	-	-	83	ns/V
ambient temperature	T_{amb}	-	-40	-	+125	$^{\circ}C$



3.3、Electrical Characteristics

3.3.1、DC Characteristics 1

($T_{amb}=25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	1.2	-	V	
		$V_{CC}=4.5\text{V}$	3.15	2.4	-	V	
		$V_{CC}=6.0\text{V}$	4.2	3.2	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	0.8	0.5	V	
		$V_{CC}=4.5\text{V}$	-	2.1	1.35	V	
		$V_{CC}=6.0\text{V}$	-	2.8	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I=V_{IH}$ or V_{IL}	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	2.0	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	4.5	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	6.0	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.98	4.32	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH}$ or V_{IL}	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	0	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	0.15	0.26	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	0.16	0.26	V
input leakage current	I_I	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	± 1.0	μA	
OFF-state output current	I_{OZ}	$V_I=V_{IH}$ or $V_{IL}; V_O=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	± 1.0	μA	
supply current	I_{CC}	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	8.0	μA	
input capacitance	C_I	-	-	3.5	-	pF	



3.3.2、DC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	-	-	V	
		$V_{CC}=4.5\text{V}$	3.15	-	-	V	
		$V_{CC}=6.0\text{V}$	4.2	-	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	-	0.5	V	
		$V_{CC}=4.5\text{V}$	-	-	1.35	V	
		$V_{CC}=6.0\text{V}$	-	-	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_O = -20\mu\text{A}; V_{CC} = 2.0\text{V}$	1.9	-	-	V
			$I_O = -20\mu\text{A}; V_{CC} = 4.5\text{V}$	4.4	-	-	V
			$I_O = -20\mu\text{A}; V_{CC} = 6.0\text{V}$	5.9	-	-	V
			$I_O = -4.0\text{mA}; V_{CC} = 4.5\text{V}$	3.84	-	-	V
			$I_O = -5.2\text{mA}; V_{CC} = 6.0\text{V}$	5.34	-	-	V
LOW-level output voltage	V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_O = 20\mu\text{A}; V_{CC} = 2.0\text{V}$	-	-	0.1	V
			$I_O = 20\mu\text{A}; V_{CC} = 4.5\text{V}$	-	-	0.1	V
			$I_O = 20\mu\text{A}; V_{CC} = 6.0\text{V}$	-	-	0.1	V
			$I_O = 4.0\text{mA}; V_{CC} = 4.5\text{V}$	-	-	0.33	V
			$I_O = 5.2\text{mA}; V_{CC} = 6.0\text{V}$	-	-	0.33	V
input leakage current	I_I	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0\text{V}$	-	-	± 1.0	μA	
OFF-state output current	I_{OZ}	$V_I = V_{IH}$ or $V_{IL}; V_O = V_{CC}$ or GND; $V_{CC} = 6.0\text{V}$	-	-	± 5.0	μA	
supply current	I_{CC}	$V_I = V_{CC}$ or GND; $I_O = 0\text{A}; V_{CC} = 6.0\text{V}$	-	-	80	μA	



3.3.3、DC Characteristics 3

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	-	-	V	
		$V_{CC}=4.5\text{V}$	3.15	-	-	V	
		$V_{CC}=6.0\text{V}$	4.2	-	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	-	0.5	V	
		$V_{CC}=4.5\text{V}$	-	-	1.35	V	
		$V_{CC}=6.0\text{V}$	-	-	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_O = -20\mu\text{A}; V_{CC} = 2.0\text{V}$	1.9	-	-	V
			$I_O = -20\mu\text{A}; V_{CC} = 4.5\text{V}$	4.4	-	-	V
			$I_O = -20\mu\text{A}; V_{CC} = 6.0\text{V}$	5.9	-	-	V
			$I_O = -4.0\text{mA}; V_{CC} = 4.5\text{V}$	3.7	-	-	V
			$I_O = -5.2\text{mA}; V_{CC} = 6.0\text{V}$	5.2	-	-	V
LOW-level output voltage	V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_O = 20\mu\text{A}; V_{CC} = 2.0\text{V}$	-	-	0.1	V
			$I_O = 20\mu\text{A}; V_{CC} = 4.5\text{V}$	-	-	0.1	V
			$I_O = 20\mu\text{A}; V_{CC} = 6.0\text{V}$	-	-	0.1	V
			$I_O = 4.0\text{mA}; V_{CC} = 4.5\text{V}$	-	-	0.4	V
			$I_O = 5.2\text{mA}; V_{CC} = 6.0\text{V}$	-	-	0.4	V
input leakage current	I_I	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0\text{V}$	-	-	± 1.0	μA	
OFF-state output current	I_{OZ}	$V_I = V_{IH}$ or $V_{IL}; V_O = V_{CC}$ or GND; $V_{CC} = 6.0\text{V}$	-	-	± 10	μA	
supply current	I_{CC}	$V_I = V_{CC}$ or GND; $I_O = 0\text{A}; V_{CC} = 6.0\text{V}$	-	-	160	μA	



3.3.4、AC Characteristics 1

($T_{amb}=25^{\circ}C$, $GND=0V$, $C_L=50pF$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
propagation delay	t_{pd}	nAn to n \bar{Y} n; see Figure 6 ^[1]	$V_{CC}=2.0V$	-	39	145	ns
			$V_{CC}=4.5V$	-	14	29	ns
			$V_{CC}=5.0V$; $C_L=15pF$	-	11	-	ns
			$V_{CC}=6.0V$	-	11	25	ns
		n \bar{E} to n \bar{Y} n; see Figure 7 ^[2]	$V_{CC}=2.0V$	-	33	135	ns
			$V_{CC}=4.5V$	-	12	27	ns
			$V_{CC}=5.0V$; $C_L=15pF$	-	10	-	ns
			$V_{CC}=6.0V$	-	10	23	ns
transition time	t_t	n \bar{Y} n; see Figure 6 and Figure 7 ^[2]	$V_{CC}=2.0V$	-	19	75	ns
			$V_{CC}=4.5V$	-	7	15	ns
			$V_{CC}=6.0V$	-	6	13	ns
power dissipation capacitance	C_{PD}	$C_L=50pF$; $f=1MHz$; $V_I=GND$ to V_{CC} ^[3]	-	42	-	pF	

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_t is the same as t_{THL} and t_{TLH} .

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D=C_{PD}\times V_{CC}^2\times f_i\times N+\sum(C_L\times V_{CC}^2\times f_o)$ where:

f_i =input frequency in MHz;

f_o =output frequency in MHz;

C_L =output load capacitance in pF;

V_{CC} =supply voltage in V;

N =number of inputs switching;

$\sum(C_L\times V_{CC}^2\times f_o)$ =sum of outputs.



3.3.5、AC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $GND = 0\text{V}$, $C_L = 50\text{pF}$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
propagation delay	t_{pd}	nAn to $n\bar{Y}n$; see Figure 6 ^[1]	$V_{CC} = 2.0\text{V}$	-	-	180	ns
			$V_{CC} = 4.5\text{V}$	-	-	36	ns
			$V_{CC} = 6.0\text{V}$	-	-	31	ns
		$n\bar{E}$ to $n\bar{Y}n$; see Figure 7 ^[1]	$V_{CC} = 2.0\text{V}$	-	-	170	ns
			$V_{CC} = 4.5\text{V}$	-	-	34	ns
			$V_{CC} = 6.0\text{V}$	-	-	29	ns
transition time	t_t	$n\bar{Y}n$; see Figure 6 and Figure 7 ^[2]	$V_{CC} = 2.0\text{V}$	-	-	95	ns
			$V_{CC} = 4.5\text{V}$	-	-	19	ns
			$V_{CC} = 6.0\text{V}$	-	-	16	ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_t is the same as t_{THL} and t_{TLH} .



3.3.6、AC Characteristics 3

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $GND = 0\text{V}$, $C_L = 50\text{pF}$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
propagation delay	t_{pd}	nAn to n \bar{Y} n; see Figure 6 ^[1]	$V_{CC} = 2.0\text{V}$	-	-	220	ns
			$V_{CC} = 4.5\text{V}$	-	-	44	ns
			$V_{CC} = 6.0\text{V}$	-	-	38	ns
		n \bar{E} to n \bar{Y} n; see Figure 7 ^[1]	$V_{CC} = 2.0\text{V}$	-	-	205	ns
			$V_{CC} = 4.5\text{V}$	-	-	41	ns
			$V_{CC} = 6.0\text{V}$	-	-	35	ns
transition time	t_t	n \bar{Y} n; see Figure 6 and Figure 7 ^[2]	$V_{CC} = 2.0\text{V}$	-	-	110	ns
			$V_{CC} = 4.5\text{V}$	-	-	22	ns
			$V_{CC} = 6.0\text{V}$	-	-	19	ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_t is the same as t_{THL} and t_{TLH} .

4、Testing Circuit

4.1、AC Testing Circuit

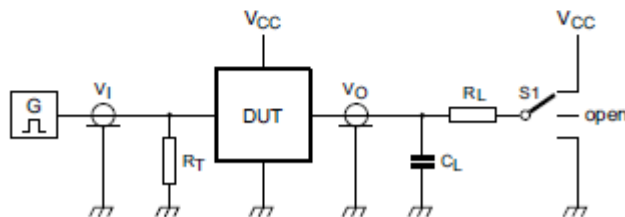
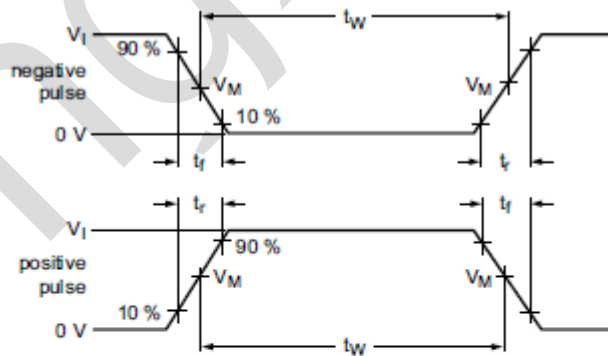


Figure 5. Test circuit for measuring switching times



Definitions for test circuit:

C_L =Load capacitance including jig and probe capacitance.

R_T =Termination resistance should be equal to the output impedance Z_o of the pulse generator.

R_L =Load resistance.

S1=Test selection switch.

4.2、 AC Testing Waveforms

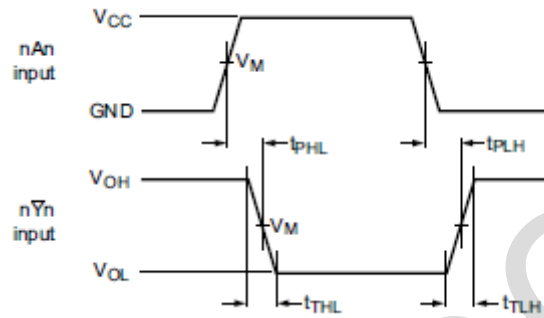


Figure 6. Propagation delay input ($n\bar{A}n$) to output ($n\bar{Y}n$) and transition time output ($n\bar{Y}n$)

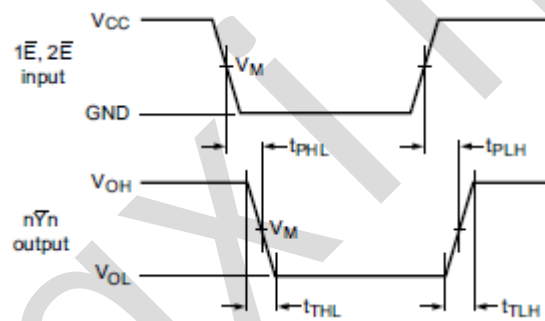


Figure 7. Propagation delay enable input ($n\bar{E}$) to output ($n\bar{Y}n$) and transition time output ($n\bar{Y}n$)

4.3、 Measurement Points

Input	Output
V_M	V_M
$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

4.4、 Test Data

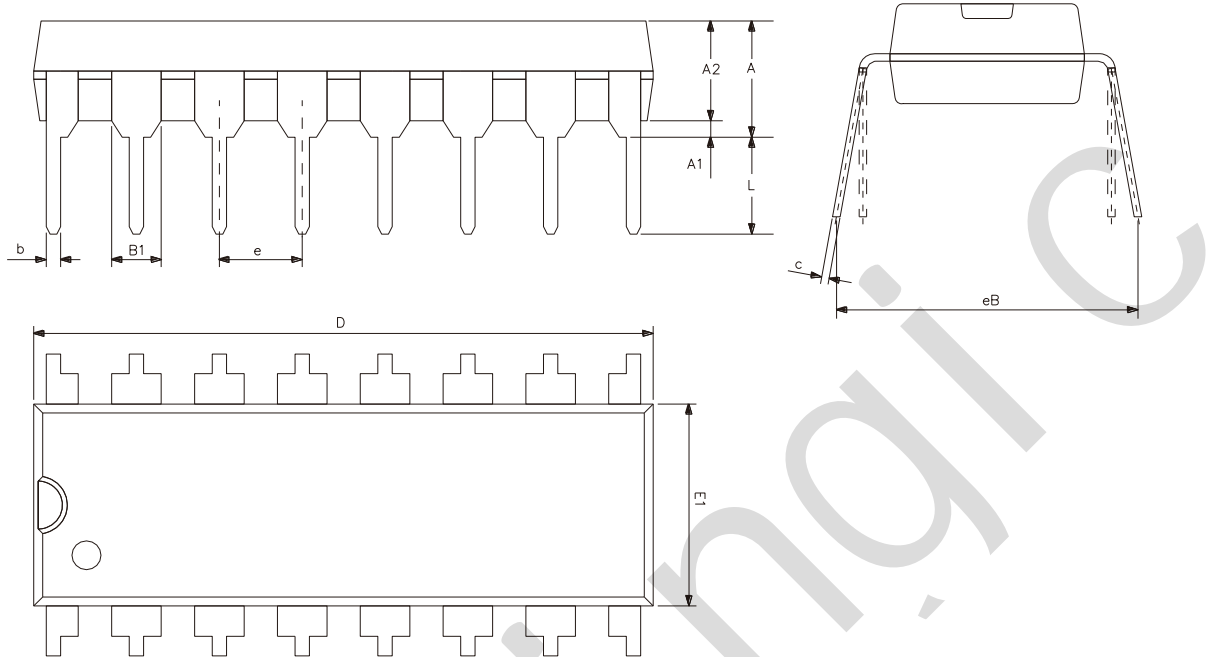
Input		Load		S1 position		
V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
V_{CC}	6ns	15pF, 50pF	1k Ω	open	GND	V_{CC}



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5、Package Information

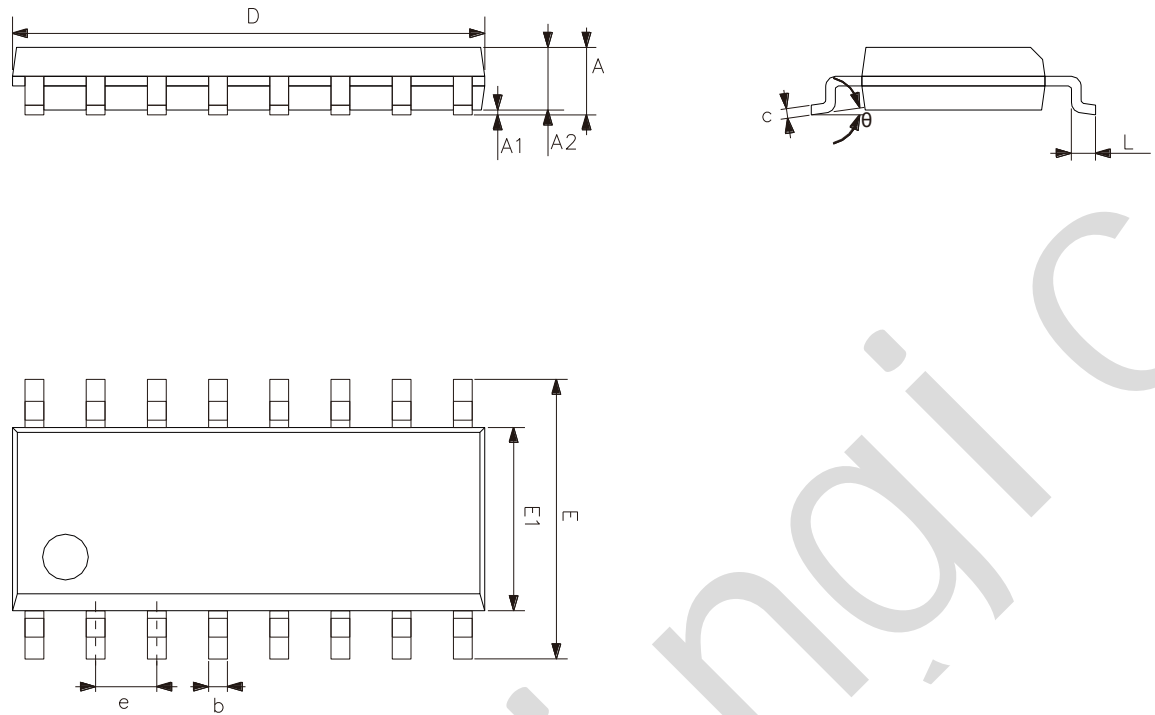
5.1、DIP16



Symbol	Dimensions (mm)	
	Min.	Max.
A2	3.20	3.60
A1	0.51	-
A	3.60	5.33
L	3.00	3.60
b	0.36	0.56
B1	1.52	
D	18.80	19.94
E1	6.20	6.60
e	2.54	
c	0.20	0.36
eB	7.62	9.30



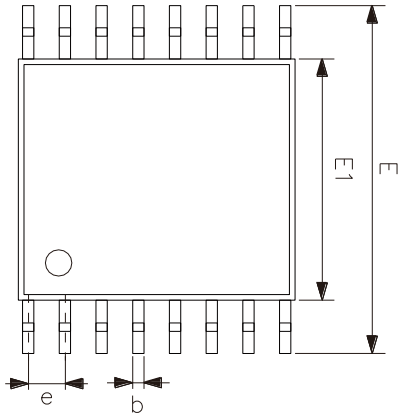
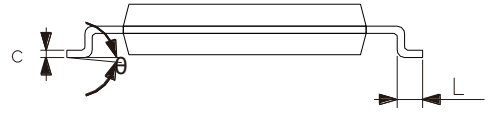
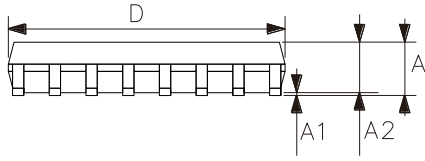
5.2、SOP16



Symbol	Dimensions (mm)	
	Min.	Max.
A	1.35	1.80
A1	0.10	0.25
A2	1.25	1.55
b	0.33	0.51
c	0.19	0.25
D	9.50	10.10
E	5.80	6.30
E1	3.70	4.10
e	1.27	
L	0.35	0.89
θ	0°	8°



5.3、TSSOP16



Symbol	Dimensions (mm)	
	Min.	Max.
A	-	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E1	4.30	4.50
E	6.20	6.60
e	0.65	
L	0.45	0.75
θ	0°	8°



6、 Statements And Notes

6.1、 The name and content of Hazardous substances or Elements in the product

Part name	Hazardous substances or Elements									
	Lead and lead compounds	Mercury and mercury compounds	Cadmium and cadmium compounds	Hexavalent chromium compounds	Polybrominated biphenyls	Polybrominated biphenyl ethers	Dibutyl phthalate	Butylbenzyl phthalate	Di-2-ethylhexyl phthalate	Diisobutyl phthalate
Lead frame	○	○	○	○	○	○	○	○	○	○
Plastic resin	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
The lead	○	○	○	○	○	○	○	○	○	○
Plastic sheet installed	○	○	○	○	○	○	○	○	○	○
explanation	○: Indicates that the content of hazardous substances or elements in the detection limit of the following the SJ/T11363-2006 standard. ×: Indicates that the content of hazardous substances or elements exceeding the SJ/T11363-2006 Standard limit requirements.									

6.2、 Notes

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